

ABSTRACT OF THE DISCLOSURE

A wafer space supporting apparatus is installed on a support chuck to relieve physical stress caused by thermal expansion or contraction of an object to be fabricated and adjusts itself to support the object to compensate for thermal expansion and contraction as well as minimize hard defects generated. The wafer space supporting apparatus includes a plurality of sliding pockets sunken into the supporting surface of the chuck, and sliding pads respectively floating-coupled in the sliding pockets such that they are spaced apart from the supporting surface so that they may adapt to expansions and contractions of an object to be fabricated, thereby preventing or minimizing any hard defects or physical stress.

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